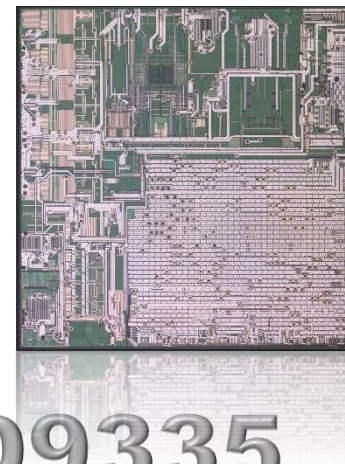
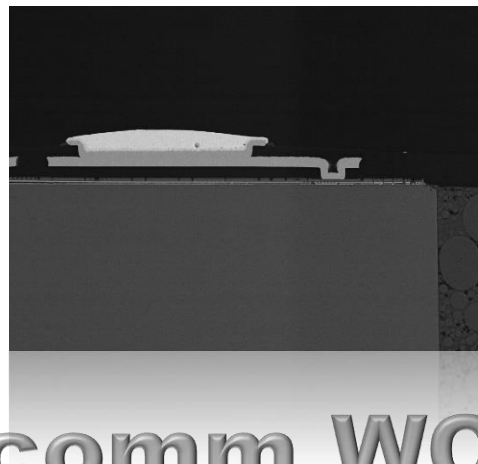


Reverse Costing Analysis



Qualcomm WCD9335 Fan-Out WLP Audio Codec

April 2016 – Version 1 – Written by Stéphane ELISABETH

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Glossary

1. Overview / Introduction	4
– Executive Summary	
– Reverse Costing Methodology	
2. Company Profile	7
– Qualcomm	
– Snapdragon 820 Chipset	
3. Physical Analysis	13
– Synthesis of the Physical Analysis	
– Samsung Galaxy S7 Teardown	15
– Smartphone Disassembly & Component Removal	
– eWLB Package Analysis	21
– View, Dimensions & Marking	
– eWLB Package	
– eWLB Package Cross-Section	
– eWLB Redistribution Layer	
– Summary of Physical Data	
– Die Analysis	37
– View, Dimensions & Marking	
– Die Main Blocks ID	
– Die Process	
– Die Cross-Section Analysis	47
– Die Cross-section	
– Metal Layer Cross Section	
– Process Characteristics	
4. Manufacturing Process Flow	53
– Chip Fabrication Unit	
– eWLB Fabrication Unit	
– eWLB Process Flow	

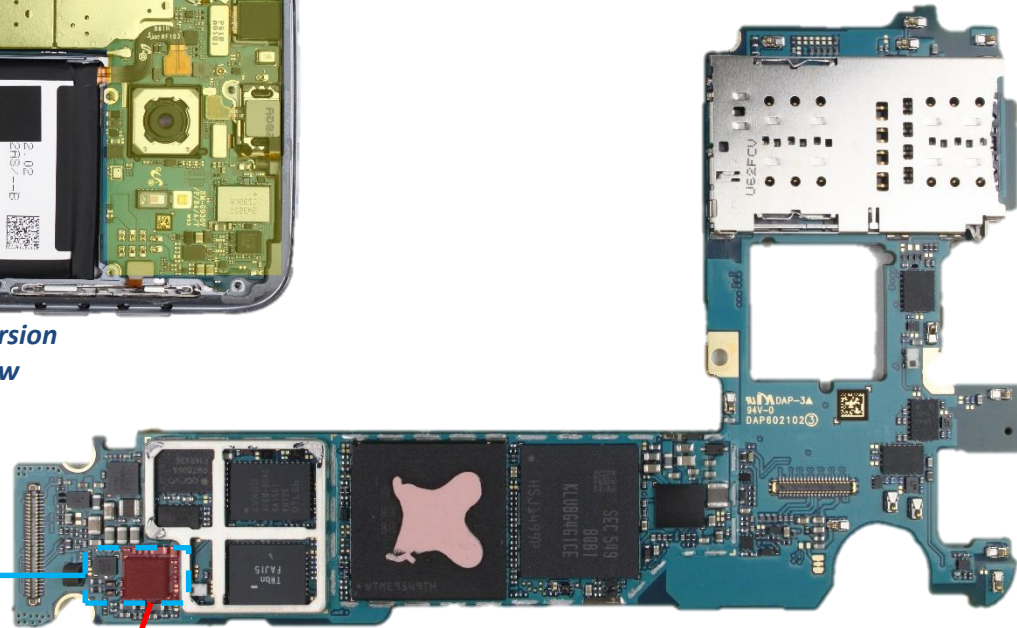
5. Cost Analysis	64
– Synthesis of the cost analysis	
– Main steps of economic analysis	
– Yields Hypotheses	
– Die Cost Analysis	69
– Wafer Front-End Cost	
– Probe Test Cost	
– Die Cost	
– eWLB Package Cost Analysis	73
– eWLB Wafer Cost	
– eWLB Cost per Process Step	
– Component Cost	78
6. Cost Analysis Simulation without Fan-Out Packaging	80
– Die Cost	
– WLP Package Cost	
– Component Cost Comparison	
7. Estimated Price Analysis	86
– Manufacturer Financial Ratios	
– Estimated Selling Price	
8. Package Comparison	89
– Fan-Out Comparison	
– Package process Comparison	
– Synthesis Comparison	
Contact	93

- This full reverse costing study has been conducted to provide insight on technology data, manufacturing cost and selling price of the **Qualcomm WCD9335 Fan-Out WLP Audio Codec**.
- The Audio codec from Qualcomm should be found in all smartphone using Snapdragon 820 chipset. The packaging use fan-out technology. Actually more than 100 models all around the world featured the entire chipset, among them the Samsung Galaxy S7 and S7 Edge in their US version.
- The WCD9335 is an audio codec from Qualcomm for smartphone. The WCD9335 is featuring a die packaged in a fan-out technology.
- **The analysis is focused on the fan-out packaging.**
- The package corresponds to wafer-level package licensed by Intel/Infineon called eWLB (embedded Wafer Level Ball Grid Array).
- Based on a complete physical analysis of the WCD9335 component, this report provides the manufacturing cost of the component. It will be compared to other **Fan-out package from Infineon and NXP**.



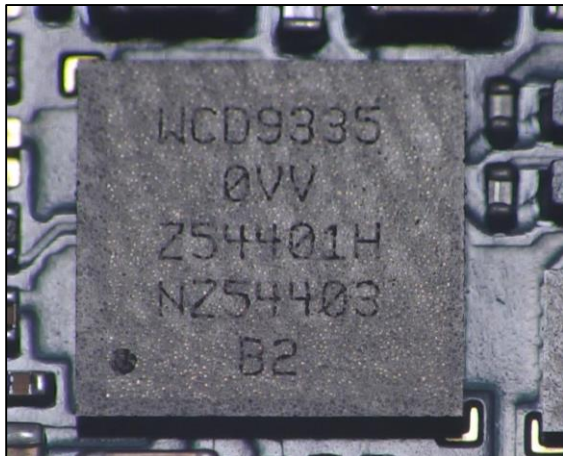
*Samsung S7 US Version
Main Board view*

Audio area

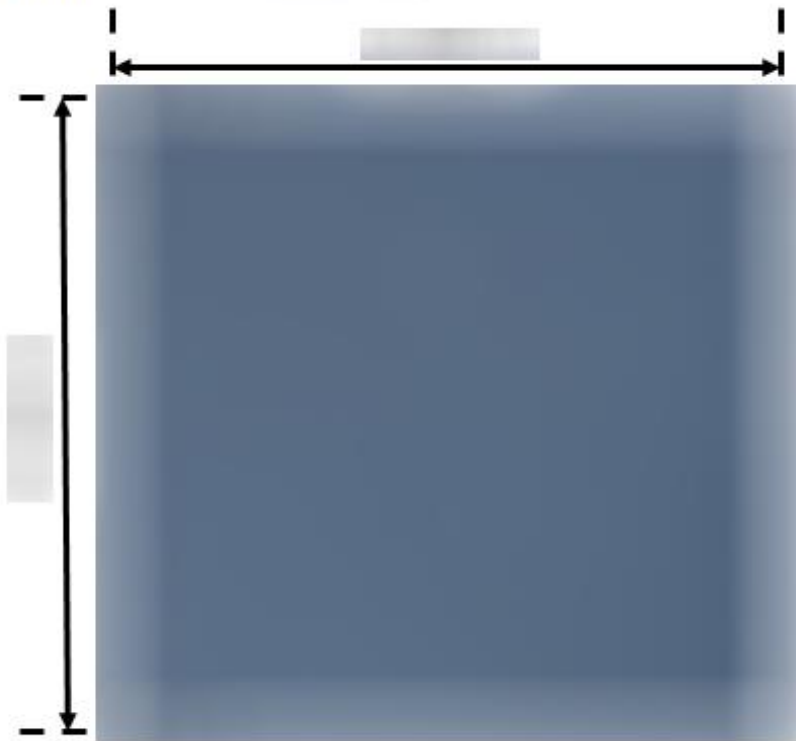


*Samsung S7 US Version
Main Board (Bottom view)*

- The Audio Codec chip is located on the main board.



- Package:
- Dimensions:
- Pin Pitch:



Package top view



Package bottom view



Package Side View

(1)

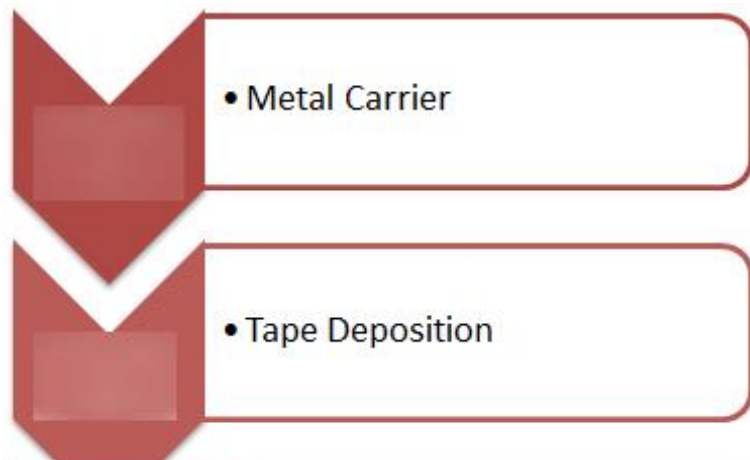


Package Cross-Section – Optical view (1)



Details Package Cross-Section – SEM view

Details Package Cross-Section – SEM view

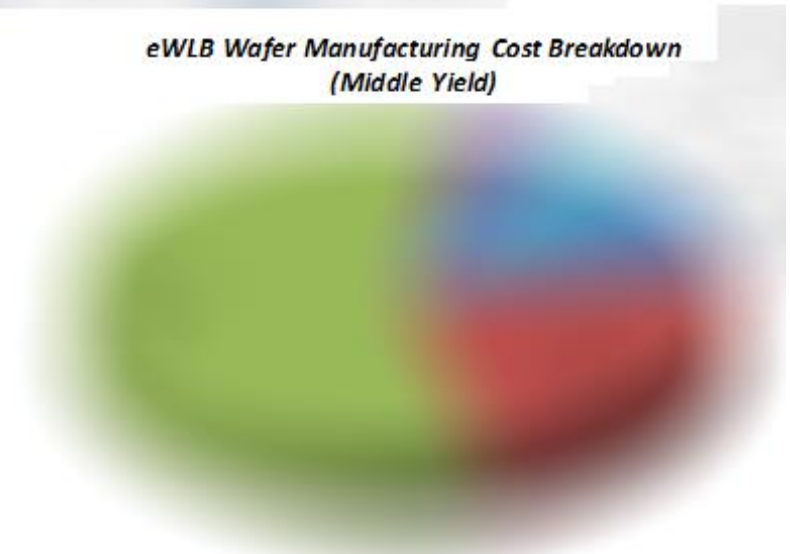


Dies Cost	Low Yield		Medium Yield		High Yield	
	Cost	Breakdown	Cost	Breakdown	Cost	Breakdown
Die Cost						
Dies per eWLB Wafer						
Dies Cost per eWLB Wafer						

eWLB Manufacturing 300mm	Low Yield		Medium Yield		High Yield	
	Cost	Breakdown	Cost	Breakdown	Cost	Breakdown
Clean Room Cost						
Equipment Cost						
Consumable Cost						
Labor Cost						
Yield losses						
eWLB Manufacturing Cost						
eWLB Manufacturing Price						

*eWLB Wafer Manufacturing Cost Breakdown
(Middle Yield)*

- The eWLB manufacturing cost ranges from [redacted] according to yield and function variations.
- The largest portion of the manufacturing cost is due to the [redacted]
- We estimate a gross margin of 25 % for the package manufacturer [redacted] which results in a packaging price ranging from [redacted]. This corresponds to the selling price to Qualcomm.

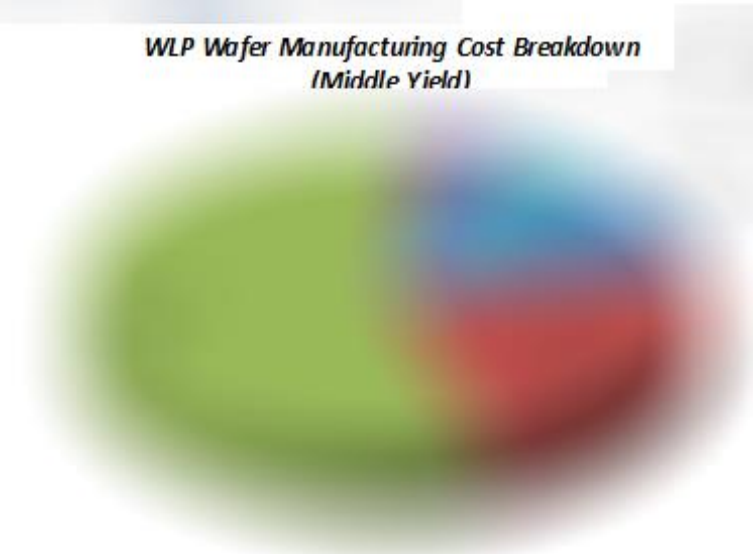


Die Cost	Low Yield		Medium Yield		High Yield	
	Cost	Breakdown	Cost	Breakdown	Cost	Breakdown
Die Cost						
Dies per WLP Wafer						
Dies Cost per WLP Wafer						

eWLB Manufacturing 300mm	Low Yield		Medium Yield		High Yield	
	Cost	Breakdown	Cost	Breakdown	Cost	Breakdown
Clean Room Cost						
Equipment Cost						
Consumable Cost						
Labor Cost						
Yield losses						
WLP Manufacturing Cost						
WLP Manufacturing Price						

WLP Wafer Manufacturing Cost Breakdown
(Middle Yield)

- The **WLP packaging** manufacturing cost ranges from [redacted] according to yield and function variations.
- The largest portion of the manufacturing cost is due to the [redacted]
- We estimate a **gross margin of 25 %** for the package manufacturer [redacted] which results in a **Package price** ranging from [redacted]



eWLB Manufacturing Step Cost Breakdown

EWLB Manufacturing Step Cost Breakdown

eWLB Package for Qualcomm

RCP Manufacturing Step Cost Breakdown

Infineon eWLB Package

Nepes RCP Package

-

Reverse costing analysis represents the best cost/price evaluation given the publically available data, and estimates completed by industry experts.

Given the hypothesis presented in this analysis, the major sources of correction would lead to a +/- 10% correction on the manufacturing cost (if all parameters are cumulated).

These results are open for discussion. We can reevaluate this circuit with your information. Please contact us:

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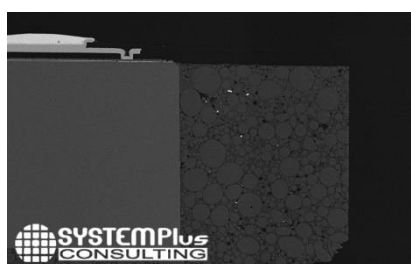
SYSTEM

POWER

Qualcomm WCD9335

Fan-Out WLP Audio Codec

*Qualcomm's Fan-Out Wafer-Level Package Chip
Audio Codec in eWLB Package inside Samsung Galaxy S7 and S7 Edge*



Snapdragon 820 chipset. In this chipset, we discovered for the first time a Qualcomm component featuring Fan-Out Wafer-Level Packaging (FOWLP): the Qualcomm Audio Codec WCD9335.

Located on the smartphone's main board, the audio codec chip's presence in the Samsung Galaxy S7 and S7 Edge depends on the smartphone version. The international version, featuring an Exynos chipset, integrates the audio codec chip from Cirrus Logic. The U.S. version, featuring the Snapdragon 820 chipset, integrates the audio codec from Qualcomm.

The Qualcomm WDC9335 is wafer-level packaged with fan-out technology. This is still relatively rare in the smartphone market but is expected to spread quickly. The FOWLP technology used is the eWLB, licensed by Intel/Infineon to several OSATs including ASE Group, Nanium, and STATS ChipPAC.

Thanks to this FOWLP process, Qualcomm is able to propose a very small die independent of the area required by the I/O pads. The result is a very cost-effective component that can compete with a standard fan-in WLP technology.

This report includes a comparison with the audio codec solution from Cirrus Logic for the international version, which uses a standard fan-in WLP technology. It also features comparisons with FOWLP technologies like RCP from NXP/nepes, and eWLB 1st-generation from Infineon.

Title: Qualcomm WCD9335
Fan-Out WLP Audio Codec

Pages: 93

Date: April 2016

Format: PDF & Excel file

Price: Full report: EUR 3,290

COMPLETE TEARDOWN WITH:

- Detailed photos
- Precise measurements
- Material analysis
- Manufacturing process flow
- Supply-chain evaluation
- Manufacturing cost analysis
- Estimated sales price
- Comparison with Cirrus Fan-In WLP Audio Codec in Samsung S7 European Version
- Comparison with Intel/Infineon's eWLB & NXP/nepes RCP

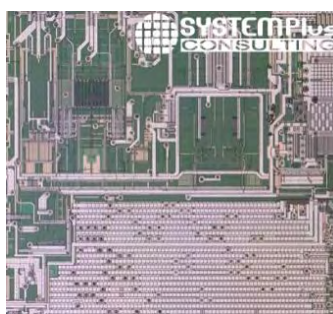
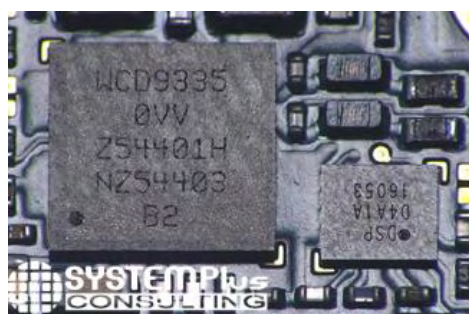


TABLE OF CONTENTS

Overview/Introduction

Company Profile & Supply Chain

Physical Analysis

Physical Analysis Methodology

- Samsung Galaxy S7 Teardown
 - ✓ Component removal
- Fan-Out Packaging Analysis
 - ✓ Package view, dimensions & marking
 - ✓ Fan-out package cross-section
 - ✓ Fan-out package process
- Die Analysis
 - ✓ Die view, dimensions & marking
 - ✓ Die cross-section
 - ✓ Die process

Manufacturing Process Flow

- Chip Fabrication Unit
- eWLB Fabrication Unit
- eWLB Process Flow

Cost Analysis

- Synthesis of the Cost Analysis
- Die Cost Analysis
 - ✓ Wafer front-end cost
 - ✓ Probe test cost
 - ✓ Die cost
- eWLB Cost Analysis
 - ✓ eWLB wafer cost
 - ✓ eWLB cost per process step
- Component Cost

Cost Analysis Simulation Without eWLB Packaging

- ✓ Die cost
- ✓ WLP package cost
- ✓ Component cost comparison

Estimated Price Analysis

- Manufacturer Financial Ratios
- Estimated Sales Price

Technology and Cost Comparison with Infineon's eWLB and NXP's RCP



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Dr Stéphane Elisabeth has joined our team this year. He has a deep knowledge of Materials characterizations and Electronics systems. He holds an Engineering Degree in Electronics and Numerical Technology, and a PhD in Materials for Microelectronics.



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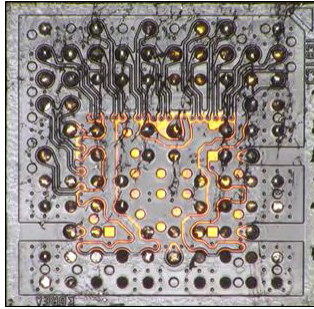
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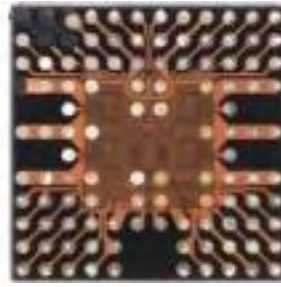
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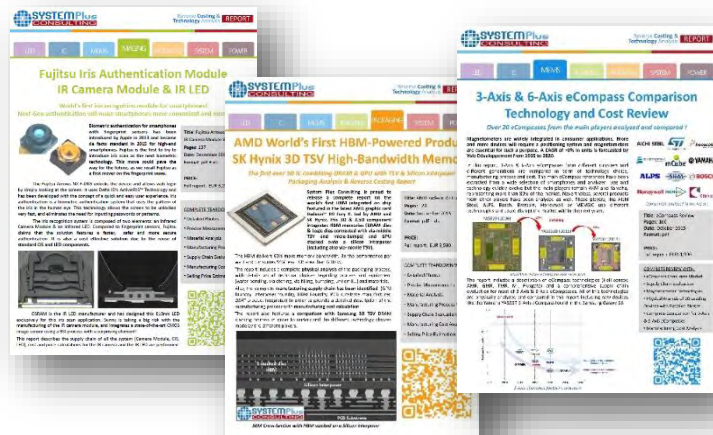
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- Posting any Product to any other online service (including bulletin boards or the Internet);

- Licensing, leasing, selling, offering for sale or assigning the Product.

6.3 The Buyer shall be solely responsible towards the Seller of all infringements of this obligation, whether this infringement comes from its employees or any person to whom the Buyer has sent the Products and shall personally take care of any related proceedings, and the Buyer shall bear related financial consequences in their entirety.

6.4 The Buyer shall define within its company point of contact for the needs of the contract. This person will be the recipient of each new report in PDF format. This person shall also be responsible for respect of the copyrights and will guaranty that the Products are not disseminated out of the company.

6.5 In the context of annual subscriptions, the person of contact shall decide who within the Buyer, shall be entitled to access on line the reports on I-micronews.com. In this respect, the Seller will give the Buyer a maximum of 10 password, unless the multiple sites organization of the Buyer requires more passwords. The Seller reserves the right to check from time to time the correct use of this password.

6.6 In the case of a multisite, multi license, only the employee of the buyer can access the report or the employee of the companies in which the buyer have 100% shares. As a matter of fact the investor of a company, the joint venture done with a third party etc..cannot access the report and should pay a full license price.

7. Termination

7.1 If the Buyer cancels the order in whole or in part or postpones the date of mailing, the Buyer shall indemnify the Seller for the entire costs that have been incurred as at the date of notification by the Buyer of such delay or cancellation. This may also apply for any other direct or indirect consequential loss that may be borne by the Seller, following this decision.

7.2 In the event of breach by one Party under these conditions or the order, the non-breaching Party may send a notification to the other by recorded delivery letter upon which, after a period of thirty (30) days without solving the problem, the non-breaching Party shall be entitled to terminate all the pending orders, without being liable for any compensation.

8. Miscellaneous

All the provisions of these Terms and Conditions are for the benefit of the Seller itself, but also for its licensors, employees and agents. Each of them is entitled to assert and enforce those provisions against the Buyer. Any notices under these Terms and Conditions shall be given in writing. They shall be effective upon receipt by the other Party.

The Seller may, from time to time, update these Terms and Conditions and the Buyer, is deemed to have accepted the latest version of these terms and conditions, provided they have been communicated to him in due time.

9. Governing law and jurisdiction

9.1 Any dispute arising out or linked to these Terms and Conditions or to any contract (orders) entered into in application of these Terms and Conditions shall be settled by the French Commercial Courts of Lyon, which shall have exclusive jurisdiction upon such issues.

9.2 French law shall govern the relation between the Buyer and the Seller, in accordance with these Terms and Conditions.

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